

Title (en)

APPARATUS FOR THERMAL TREATMENT OF THIN FILM WAFER

Title (de)

THERMISCHE BEHANDLUNGSVORRICHTUNG FÜR DÜNNE FILM-HALBLEITERBLÄTTCHEN

Title (fr)

APPAREIL DE TRAITEMENT THERMIQUE DE TRANCHES A COUCHE MINCE

Publication

**EP 0702775 A1 19960327 (EN)**

Application

**EP 95911781 A 19950215**

Priority

- KR 19940002820 A 19940217
- US 9502008 W 19950215

Abstract (en)

[origin: WO9523427A2] The apparatus of the present invention is for the thermal treatment of a thin film wafer and includes a vacuum chamber, a heater block, a holding clamp for receiving the heater block and for holding a wafer and which includes a specific weight to press the wafer against the heater block, a wafer supply means for supplying the wafer to, positioning the wafer on and removing the wafer from the holding clamp, and an elevator means for moving the holding clamp toward and away from the heater block to permit thermal treatment of the wafer in the vacuum chamber. The present invention advantageously supplies and removes the wafer together with minimizing damage to the wafer due to excess clamping force.

IPC 1-7

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IPC 8 full level

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